In The Specification:

Please amend paragraph [0003] as follows:

[0003] At present, the two principle methods of packaging a chip includes wire bonding and flip chip bonding. Fig. 1 is a schematic cross-sectional diagram showing the structure of a conventional flip chip package. As shown in Fig. 1, the chip package 100 comprises an integrated circuit carrier 110 and a chip 120. The chip 120 is set up on the first surface 112 of the IC carrier 110. Through a plurality of bumps 126, the chip 120 is electrically connected to the contact pads 116a on the IC carrier 110. In addition, the IC carrier 110 has a plurality of contacts 118 on the second surface [[~~14~~]]114 of the IC carrier [[~~10~~]]110. The contacts 118 are solder balls, contact pins or metallic bumps, for example. Furthermore, the contacts 118 are connected electrically to corresponding bumps 126 via the patterned circuit layer 130 in the IC carrier 110. Hence, these contacts 118 serve also as point of contact between the chip 120 and the contacts on a printed circuit board (not shown). Additionally, the IC carrier 110 can be classified as an organic substrate or a ceramic substrate according to the dielectric material used. The production method and electrical properties for these two types of substrate differ considerably, and thus each type of substrate has a particular area of use. The organic substrate is fabricated using material including glass epoxy resin (FR-4, FR-5), bismaleimide-triazine (BT) or epoxy resin. The organic substrate can be a multi-layered substrate fabricated using a lamination and/or a build-up method. On the whole, the fabrication cost of the organic substrate and the dielectric constant of an organic substrate are lower than a ceramic substrate. Consequently, the organic dielectric substrate is used to be the only option for fabricating chip packages chips and manufacturing printed circuit boards.